

ABSTRACT OF THE DISCLOSURE

A method for manufacturing a plurality of hybrid electronic circuits for active implantable medical devices and circuits made by the process. The process includes the following stages: a) preparing a collective plane plate-substrate (10) carrying on a first surface a pattern of contact areas (16) for chips and, on a second surface (the back), a pattern of metallization areas for components, with a repetition of the same patterns for a corresponding plurality of circuits to be made from said substrate; b) gluing on the first surface of the plate of a plurality of chips (12, 14); c) cabling (wiring-bonding) the chips (12, 14) to their corresponding contact areas (16); d) pouring a coating resin over the first surface of the plate to achieve a uniform layer of coating resin (22), e) hardening the resin; f) cutting the plate to form the plurality of individual substrates, with each substrate having on its first surface coated chips, each one of these substrates corresponding to an implantable device individual circuit, and g) mounting SMC components (38, 40, 42) and/or connector elements (44) to the second surface of each individual substrate, so as to complete the electron circuits of the active implantable medical devices.